

IN THE ABSTRACT:

Please change the abstract as follows:

~~Disclosed is a sheet for forming metal wires and method of forming the metal wires using the same.~~ A plate for forming the metal wires ~~having~~ has an engraved pattern for forming a plurality of trenches and an engraved pattern for forming a plurality of via holes. An insulating film pattern in which the trenches and the via holes are shaped is obtained using the plate. Also, a metal is buried into the trenches and the via holes by means of a damascene process to form upper metal wires electrically connected to lower metal wires. In the ~~present~~ invention, photolithography and etch processes are not employed. For this reason, reduction in the yield and reliability due to defects occurring in the photolithography and etch processes is prevented. Furthermore, the process steps are reduced to reduce the production cost and to improve productivity.